

**Amendment**  
**U.S. Patent Application No. 10/799,760**

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

Claim 1 (withdrawn). A method for producing a multi-layer device, the method comprising the steps of:

providing a substrate comprising a support region for supporting an electrical component in use;

forming an electrically conductive bond layer on a surface of the substrate, the bond surrounding the support region;

providing an encasing layer in contact with the bond layer, to encase the component between the substrate and the encasing layer; and

bonding the encasing layer to the bond layer to form a sealed cavity enclosing the component.

Claim 2 (withdrawn). A method according to claim 1, wherein the encasing layer is anodically bonded to the bond layer to form the sealed cavity.

Claim 3 (withdrawn). A method according to claim 1, wherein the substrate comprises an electrical conductor, positioned in isolation from the surface provided to receive the bond layer, to connect the component with an external contact pad.

Claim 4 (withdrawn). A method according to claim 3, wherein the conductor is formed from at least one conducting layer coupled with conducting plugs.

Claim 5 (withdrawn). A method according to claim 4, wherein the conducting layer is surrounded by dielectric layers.

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Claim 6 (withdrawn). A method according to claim 1, wherein the component is CMOS or BiCMOS circuitry.

Claim 7 (withdrawn). A method according to claim 1, wherein the component is a microsensor and/or a micro-actuator.

Claim 8 (withdrawn). A method according to claim 1, further comprising protecting the device from the electric field generated during anodic bonding by placing a conductive shielding layer on the glass wafer and connecting it to the substrate.

Claim 9 (withdrawn). A method according to claim 1, wherein a second encasing layer is bonded to a second surface of the substrate to form a second sealed cavity.

Claim 10 (withdrawn). A method according to claim 1, wherein multiple devices are produced simultaneously on the same substrate, wherein, a bond layer is formed on the surface of the substrate and comprises individual bond members, each of which surrounds a respective component, the bond members being interconnected by plural conducting links to provide an electrical contact path through the bond layer.

Claim 11 (currently amended). A multi-layer device comprising:

- a substrate;
- at least one electrical component located on the substrate;
- an electrically conductive bond layer, formed on the substrate and surrounding the electrical component ~~components~~; and
- an encasing layer, wherein the encasing layer is bonded to the bond layer to form a sealed cavity encasing the electrical component ~~components~~ therein.

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Claim 12 (original). A device according to claim 11, wherein the encasing layer is anodically bonded to the bond layer to form the sealed cavity.

Claim 13 (previously presented). A device according to claim 11, wherein the substrate comprises an electrical conductor, positioned in isolation from the surface provided to receive the bond layer, to connect the component with an external contact pad.

Claim 14 (original). A device according to claim 13, wherein the conductor is formed from at least one conducting layer coupled with conducting plugs.

Claim 15 (original). A device according to claim 14, wherein the conducting layer is surrounded by dielectric layers.

Claim 16 (previously presented). A device according to claim 11, wherein the component is CMOS or BiCMOS circuitry.

Claim 17 (previously presented). A device according to claim 11, wherein the component is a pressure sensor or an inertial sensor.

Claim 18 (previously presented). A device according to claim 11, further comprising a conductive shielding layer which is placed on the glass wafer and connected to the substrate, in order to protect the device from the electric field generated during anodic bonding.

Claim 19 (previously presented). A device according to claim 11, wherein a second encasing layer is bonded to a second surface of the substrate to form a second sealed cavity.

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Claim 20 (new). A multi-layer device comprising:

- a substrate including a support region;
- at least one electrical component located within the support region;
- an electrically conductive layer surrounding the support region; and
- an encasing layer including a cavity,

wherein the electrically conductive layer is configured to bond the encasing layer to the substrate such that the at least one electrical component is sealed within the cavity.